



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/782,270

Filed: February 18, 2004

For: INTERPOSER SUBSTRATE AND
WAFER SCALE INTERPOSER
SUBSTRATE MEMBER FOR USE WITH
FLIP-CHIP CONFIGURED
SEMICONDUCTOR DICE

Confirmation No.: 4215

Examiner: J. Clark

Group Art Unit: 2815

Attorney Docket No.: 2269-4973.1US
(00-0593.01/US)

Notice of Allowance Mailed:

January 26, 2006

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL995987189US

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P.O. Box 1450
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Sir:

Please amend the above-referenced application as follows:

OK
to enter
7/29/06
6/29/06

Amendments to the Specification begin on page 3 of this paper;

Amendments to the Claims are set forth in the listing of the claims that begins on

page 19 of this paper;

Remarks start at page 24 of this paper.